



Material Composition Declaration

EPC8010

Company Name	Efficient Power Conversion (EPC)	Web Site:	5/4/2016
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	3.1 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight (mg)	Mass (%)	Sum (%)	Mass (ppm)
Chip	Silicon	7440-21-3	2.7393	88.97	91.17	889678
	Silicon oxide	7631-86-9	0.0108	0.35		3503
	Silicon nitride	12033-89-5	0.0034	0.11		1088
	Gallium nitride	25617-97-4	0.0129	0.42		4204
	Aluminum	7429-90-5	0.0187	0.61		6074
	Aluminum nitride	24304-00-5	0.0031	0.10		1010
	Titanium	7440-32-6	0.0004	0.01		146
	Titanium nitride	25583-20-4	0.0017	0.05		538
	Copper	7440-50-8	0.0006	0.02		202
	Tungsten	7440-33-7	0.0002	0.01		57
	Polyimide		0.0160	0.52	5206	
Under Bump Metal	Titanium	7440-32-6	0.0004	0.01	1.09	129
	Nickel	7440-02-0	0.0118	0.38		3825
	Vanadium	7440-62-2	0.0000	0.00		0
	Copper	7440-50-8	0.0213	0.69		6925
Solder Bump	Tin	7440-31-5	0.2324	7.55	7.74	75479
	Silver	7440-22-4	0.0060	0.19		1935
	Copper	7440-50-8	0.0000	0.00		0
Sum in total:			3.1	100.00	100	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.